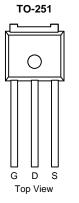
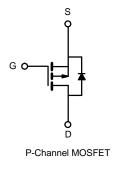


AOU405-VB Datasheet P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^d	Q _g (Typ.)		
- 30	0.018 at V _{GS} = - 10 V	- 40	13 nC		
- 30	0.022 at V _{GS} = - 4.5 V	- 35	13110		





FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- Trench Power MOSFET
- 100 % Rg Tested

APPLICATIONS

- Load Switch
- Battery Switch

ABSOLUTE MAXIMUM RATINGS T_A	= 25 °C, unless othe	erwise noted		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	- 30	V
Gate-Source Voltage		V _{GS}	± 20	v
	T _C = 25 °C		- 40	
Continuous Drain Current (T ₁ = 150 °C)	T _C = 70 °C	۱ _D	- 35	
Continuous Drain Current (1) = 130°C)	T _A = 25 °C		- 30.0 ^{a, b}	
	T _A = 70 °C		- 28 ^{a, b}	A
Pulsed Drain Current	I _{DM}	- 150		
Continuous Source-Drain Diode Current	T _C = 25 °C	I _S	- 3.5	
Continuous Source-Drain Diode Current	T _A = 25 °C	'S	- 2.1 ^{a, b}	
	T _C = 25 °C		40	
Maximum Dawar Dissinction	T _C = 70 °C	P	32	w
Maximum Power Dissipation	T _A = 25 °C	P _D	2.5 ^{a, b}	vv
	T _A = 70 °C	1	1.6 ^{a, b}	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	40	50	°C/W	
Maximum Junction-to-Foot	Steady State	R _{thJF}	24	30	C/VV	

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. t = 10 s.

c. Maximum under Steady State conditions is 95 °C/W.

d. Based on $T_C = 25$ °C.

HALOGEN

Available

SPECIFICATIONS $T_J = 25 \circ C$	C, unless oth	erwise noted				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		- 31		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			4.5		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 1.0		- 2.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			- 1 - 5	μA
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, \text{ V}_{GS} = -10 \text{ V}$	- 20		•	Α
Drain-Source On-State Resistance ^a	$V_{GS} = -10 \text{ V}, \text{ I}_{D} = -7.0 \text{ A}$		-	0.018		Ω
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 7.0 A		18		S
Dynamic ^b	013			1		
Input Capacitance	C _{iss}			1455		
Output Capacitance	C _{oss}	V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz		180		pF
Reverse Transfer Capacitance	C _{rss}			145		-
Total Gate Charge	Q _q	$V_{DC} = -15 V_{c} V_{CC} = -10 V_{c} I_{D} = -7.0 A$		25	38	
-	9			13	20	nC
Gate-Source Charge	Q _{gs}	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -7.0 \text{ A}$		3.5		
Gate-Drain Charge	Q _{gd}			5.5		
Gate Resistance	R _g	f = 1 MHz	0.4	2.0	4.0	Ω
Turn-On Delay Time	t _{d(on)}			10	20	_
Rise Time	t _r	$V_{DD} = -15 \text{ V}, \text{ R}_{L} = 2.7 \Omega$		13	20	-
Turn-Off DelayTime	t _{d(off)}	$I_{D}\cong$ - 5.6 A, V_{GEN} = - 10 V, R_{g} = 1 Ω		23	35	_
Fall Time	t _f			9	18	ns
Turn-On Delay Time	t _{d(on)}			38	57	
Rise Time	t _r	V_{DD} = - 15 V, R_L = 2.7 Ω		89	134	-
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 5.6 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		22	33	
Fall Time	t _f			11	17	
Drain-Source Body Diode Characteris	stics			1	1	
Continous Source-Drain Diode Current	۱ _S	T _C = 25 °C			- 6.5	A
Pulse Diode Forward Current	I _{SM}				- 30	
Body Diode Voltage	V _{SD}	$I_{S} = -5.6 \text{ A}, V_{GS} = 0 \text{ V}$		- 0.71	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}			22	33	ns
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = - 5.6 A, dl/dt = 100 A/μs, T _J = 25 °C		17	26	nC
Reverse Recovery Fall Time	t _a	$F = -3.6 \text{ A}, \text{ and } c = 100 \text{ A/} \mu \text{s}, \text{J} = 25 \text{ C}$		13		- ns
Reverse Recovery Rise Time	t _b			9		115

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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T_C = - 55 °C

T_C = 25 °C

2.0

2.5

3.0

T_C = 125 °C

1.5

 C_{iss}

18

- 10 V, I_D =

50

75

24

5.6 A

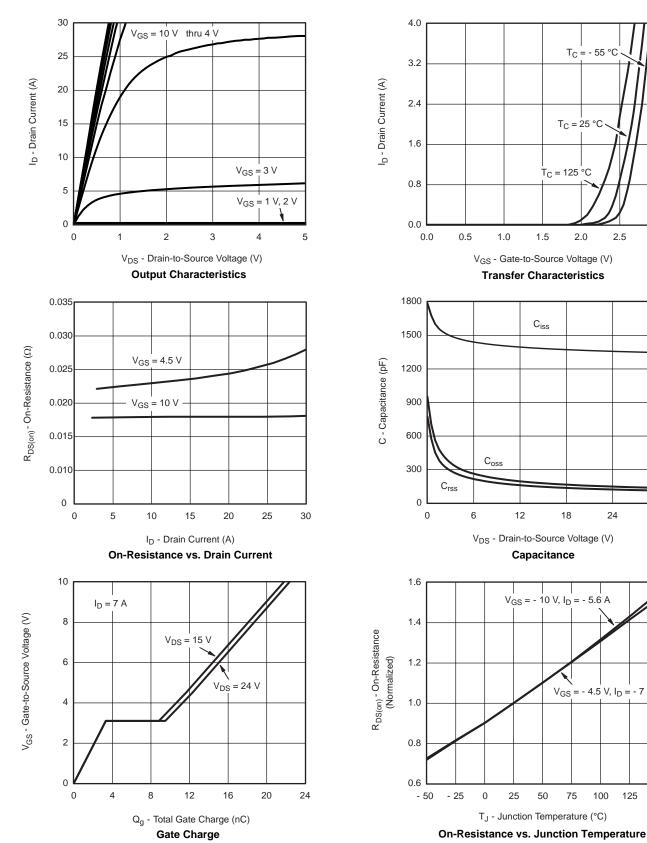
 $V_{GS} = -4.5 \text{ V}, I_D = -7 \text{ A}$

100

125

150

30



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

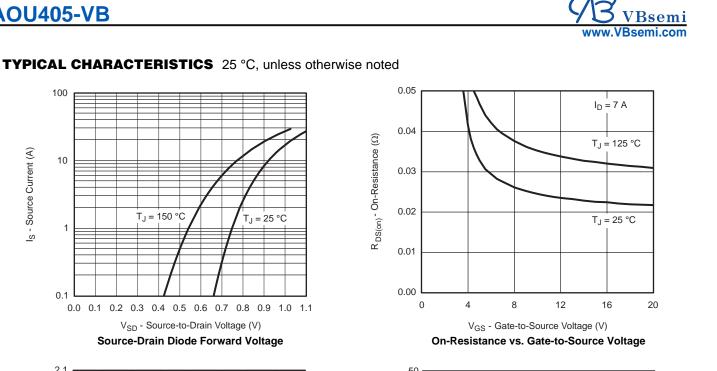
100

10

1

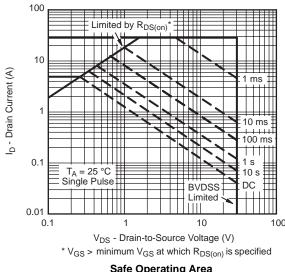
0.1

I_S - Source Current (A)



50 40 30 Power (W) 20 10 0 0.001 0.01 0.1 10 1 100 Time (s)

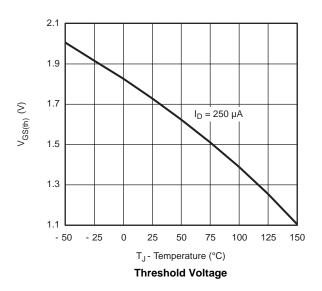
Single Pulse Power, Junction-to-Ambient

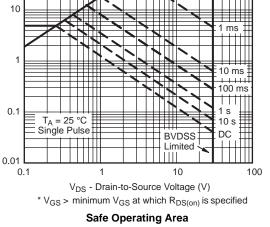


T_J = 25 °C

0.0 0.1 0.2 0.3 0.4 0.5 0.6 0.7 0.8 0.9 1.0 1.1 V_{SD} - Source-to-Drain Voltage (V) Source-Drain Diode Forward Voltage

T_J = 150 °C

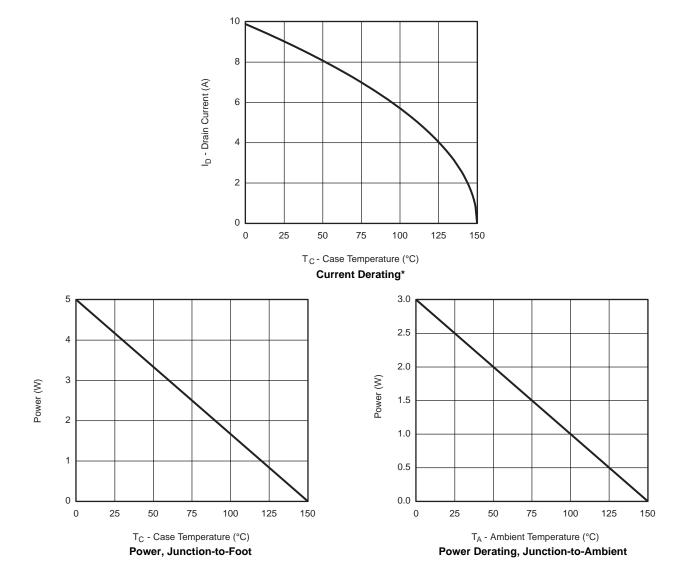








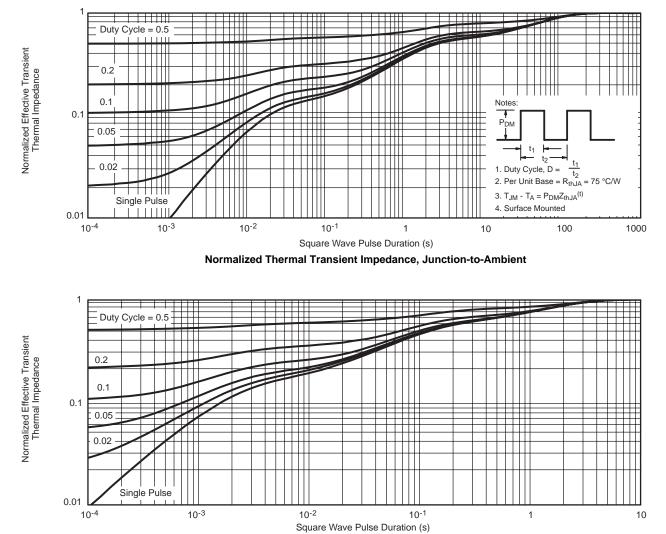
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



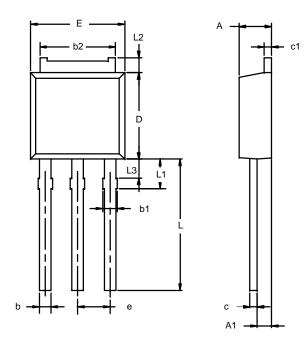
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Foot



TO-251AA (DPAK)



Note: Dimension L3 is for reference only.

	MILLIN	IETERS	INC	HES	
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
A1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
c1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
Е	6.48	6.73	0.255	0.265	
е	2.28	BSC	0.090 BSC		
L	3.89	9.53	0.153	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	
ECN: S-03946—Rev. E, 09-Jul-01 DWG: 5346					



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